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PATENT
YOR19960184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of	:	D.Y. Shih, et al.
Serial Number	:	09/254,769
Filing Date	:	March 11, 1999
Examiner	:	V. Nguyen
Group Art Unit	:	2829
For	:	WAFER SCALE HIGH DENSITY PROBE ASSEMBLY, APPARATUS FOR USE THEREOF AND METHODS OF FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated April 8, 2004, please consider the following remarks with respect to the above-identified application as follows:

REMARKS

Applicants have amended the form of claims 8 and 32 to reflect proper dependency. The objection as to improper "antecedent basis" with respect to claims 36 and 49 has been corrected.

In answer to the Examiner's objection as to claim 60, said claim is merely claiming a plurality (i.e., more than one) of the structures defined in, for example, claim 1.